Room 9

Session 2-9-1: OS05
Advanced cutting technologies I

OS05-01 Discrete analysis of the ultrasonic vibration superimposed turning process by orthogonal cutting experiments Liboriu Hendrik, Werner Jonas Maximilian, Nestler Andreas, Drossel Welf-Guntram and Schubert Andreas

OS05-02 Research on measuring point selection for strain-based on-machine estimation of workholding states
Yu Yan, Koji Teramoto, Naruki Shoji and Hiroki Matsumoto

OS05-03 Physical model of a hybrid tool consisting of SAG and face milling
Yuichi Kurane, Ashwani Pratap, Burak Sencer and Anthony Beaucamp

OS05-04 Experimental Elucidation of Cutting-edgeTemperature Behavior in Terms of Ultrasonic Vibration-assisted Drilling
Naofumi Tsuji, K. Takashima, H. Kawamura, K. Hara, R. Tanaka, A. Sakurada, K. Miyawaki and H. Isobe

Session 2-9-2: OS05
Advanced cutting technologies II

OS05-05 A Comparative Analysis of the Cutting Separation Criteria in Finite Element Simulations of Orthogonal Metal Cutting
Yaoyu Wang, Liangchi Zhang, Zhen Li and Jipeng Cui

OS05-06 Transition of cutting forces during deceleration of feed in interrupted cutting - Novel evaluation method for frictional characteristics between cutting tool and workpiece material, Isaí Espinoza-Torres, T. Ryutaro, I. Martinez-Ramirez, K. Sekiya and K. Yamada

OS05-07 Research on effect of ultra-high pressure coolant supplied from flank face in end milling of aerospace alloys supported by CFD simulations, Jingtian Mao, Kensuke Tsuchiya, Chikara Morigo and Shinji Yukinari

OS05-09 Microtexture Processing on Three-Dimensional Curved Surfaces Using Ultrasonic Milling
Keisuke hara, Atsuhiro Yoshida, Naofumi Tsuji, Kota Takashima, Hirofumi Kawamura and Hiromi Isobe

Session 2-9-3: GS17
Semiconductor manufacturing and metrology

GS17-03 New DUV Wavelength - Scanning Scatterometry for Sub-Micron High-Aspect-Ratio OCD Metrology
Fu-Sheng Yang, Min-Ru Wu, Yen-Hung Hung, Yuan-Ci Lin, Bo-Chen Kuo and Liang-Chia Chen

GS17-04 Optimizing Fourier Hyperspectral Scatterometry with Global Sensitivity Analysis for Semiconductor OCD Metrology
Yen-Hung Hung, Min-Ru Wu, Fu-Sheng Yang, Bo-Chen Kuo, Yuan-Ci Lin, Surajit Das and Liang-Chia Chen

GS17-05 Basic study of plasma dicing for SiC wafer using high-pressure plasma
Shunto Iden, Yuken Matsumura, Jumpei Yamada, Daisetsu Toh, Kazuto Yamauchi and Yasuhisa Sano

GS17-06 Dimension reduction of electromagnetic field on the top surface of 3D through silicon via array by using singular value decomposition
Song-En Chen, Chih-Chung Wang and Jia-Han Li

GS12-09 A High-precision Displacement Measurement Method based on Ultrasonic Travelling Waves in Crystals
Mingshu Wu, Bai Ji, Guancoing Tao, Yuge Zhang and Fu Min